

Objective

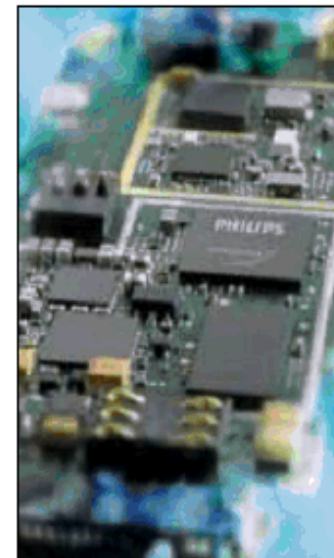
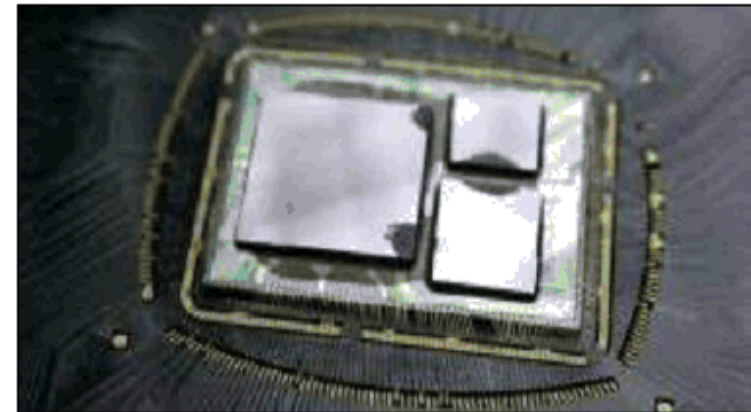
Removal of the OSP-layer on the lead frame which is necessary to prevent damaging or contamination of the top layer of the lead frames, to improve adhesion of packaging.

Research topics

- Plasma cleaning was investigated to remove the OSP-layer. This procedure was regarded as adequate

Industrial benefits

- A plasma cleaning step was introduced in the process
- Extra investment of about 150 kEuro
- Due to a lower moisture level a reduction of cost of sealing/packaging of about 500 kEuro/year



Improvement of adhesion between lead frame and package – NXP